

L. Number	Hits	Search Text	DB	Time stamp
1	33	semiconductor and (under adj ball adj metallurgy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 17:18
2	0	(semiconductor and (under adj ball adj metallurgy)) and adhesion and wettable and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 17:19
3	5	(semiconductor and (under adj ball adj metallurgy)) and vanadium and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/20 17:19

L Number	Hits	Search Text	DB	Time stamp
1	2492	(257/772,779,780,781,761).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/20 17:32
2	2534	(257/762,763,764,766).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/20 17:32